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### Understanding Embedded - FPGAs (Field Programmable Gate Array)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

### Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

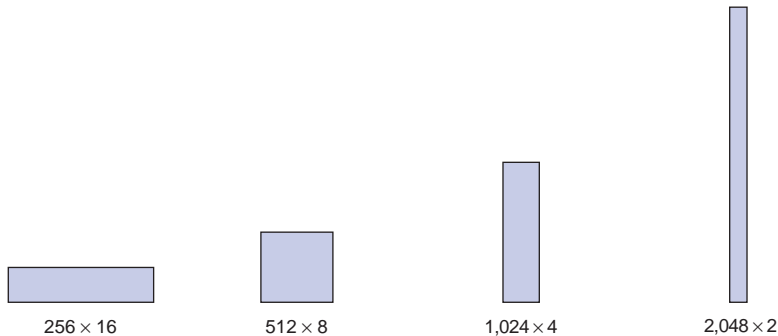
#### Details

Product Status	Obsolete
Number of LABs/CLBs	360
Number of Logic Elements/Cells	2880
Total RAM Bits	40960
Number of I/O	249
Number of Gates	199000
Voltage - Supply	2.375V ~ 2.625V
Mounting Type	Surface Mount
Operating Temperature	0°C ~ 70°C (TA)
Package / Case	484-BBGA
Supplier Device Package	484-FBGA (23x23)
Purchase URL	<a href="https://www.e-xfl.com/product-detail/intel/ep1k50fc484-1n">https://www.e-xfl.com/product-detail/intel/ep1k50fc484-1n</a>

EABs can be used to implement synchronous RAM, which is easier to use than asynchronous RAM. A circuit using asynchronous RAM must generate the RAM write enable signal, while ensuring that its data and address signals meet setup and hold time specifications relative to the write enable signal. In contrast, the EAB's synchronous RAM generates its own write enable signal and is self-timed with respect to the input or write clock. A circuit using the EAB's self-timed RAM must only meet the setup and hold time specifications of the global clock.

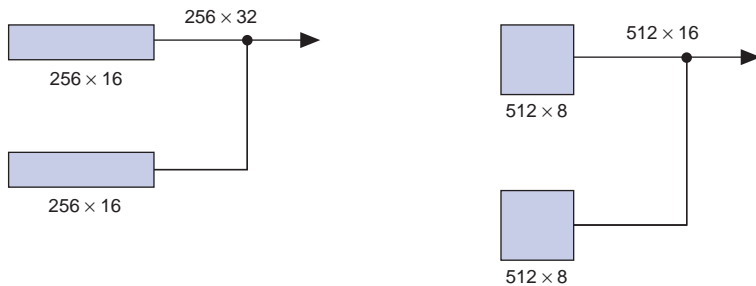
When used as RAM, each EAB can be configured in any of the following sizes:  $256 \times 16$ ;  $512 \times 8$ ;  $1,024 \times 4$ ; or  $2,048 \times 2$ . Figure 5 shows the ACEX 1K EAB memory configurations.

Figure 5. ACEX 1K EAB Memory Configurations



Larger blocks of RAM are created by combining multiple EABs. For example, two  $256 \times 16$  RAM blocks can be combined to form a  $256 \times 32$  block, and two  $512 \times 8$  RAM blocks can be combined to form a  $512 \times 16$  block. Figure 6 shows examples of multiple EAB combination.

Figure 6. Examples of Combining ACEX 1K EABs



If necessary, all EABs in a device can be cascaded to form a single RAM block. EABs can be cascaded to form RAM blocks of up to 2,048 words without impacting timing. Altera software automatically combines EABs to meet a designer's RAM specifications.

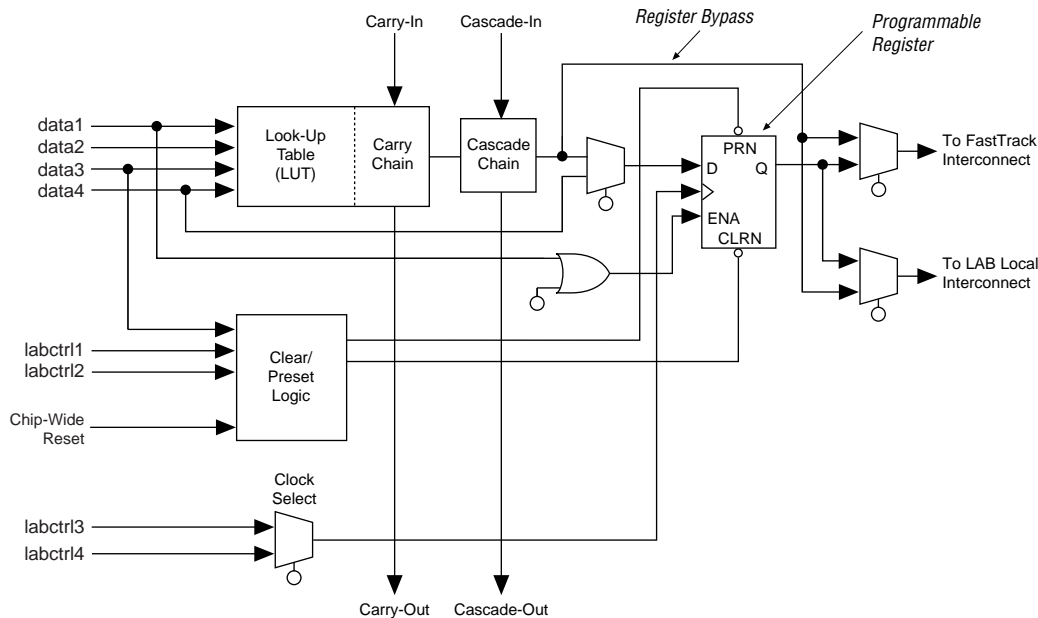
EABs provide flexible options for driving and controlling clock signals. Different clocks and clock enables can be used for reading and writing to the EAB. Registers can be independently inserted on the data input, EAB output, write address, write enable signals, read address, and read enable signals. The global signals and the EAB local interconnect can drive write-enable, read-enable, and clock-enable signals. The global signals, dedicated clock pins, and EAB local interconnect can drive the EAB clock signals. Because the LEs drive the EAB local interconnect, the LEs can control write-enable, read-enable, clear, clock, and clock-enable signals.

An EAB is fed by a row interconnect and can drive out to row and column interconnects. Each EAB output can drive up to two row channels and up to two column channels; the unused row channel can be driven by other LEs. This feature increases the routing resources available for EAB outputs (see [Figures 2 and 4](#)). The column interconnect, which is adjacent to the EAB, has twice as many channels as other columns in the device.

## Logic Array Block

An LAB consists of eight LEs, their associated carry and cascade chains, LAB control signals, and the LAB local interconnect. The LAB provides the coarse-grained structure to the ACEX 1K architecture, facilitating efficient routing with optimum device utilization and high performance. [Figure 7](#) shows the ACEX 1K LAB.

Figure 8. ACEX 1K Logic Element

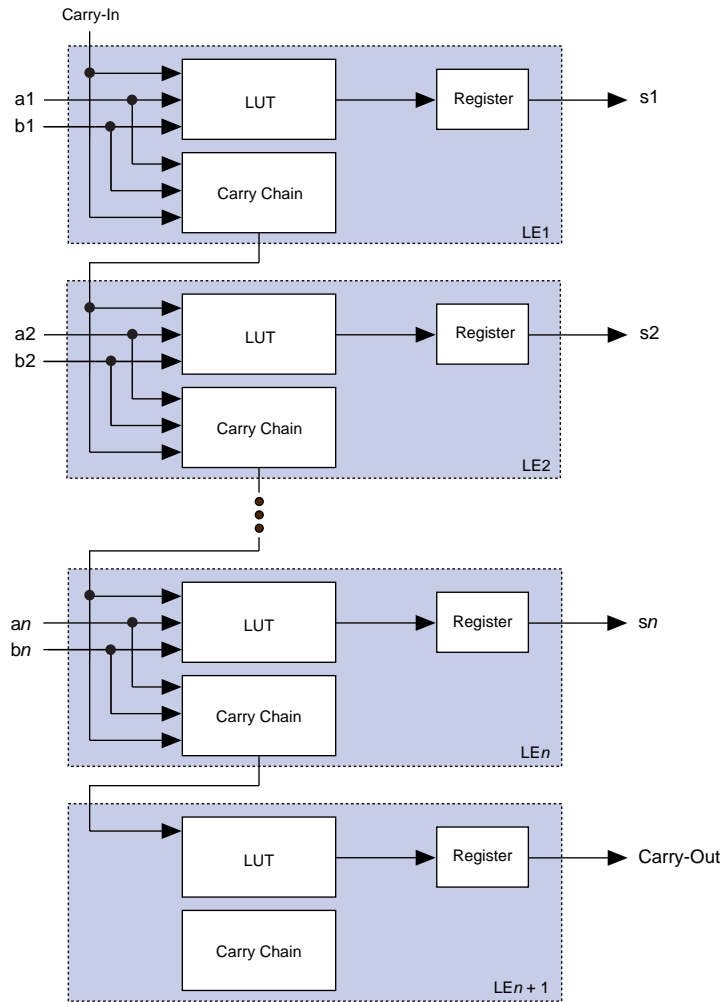


The programmable flipflop in the LE can be configured for D, T, JK, or SR operation. The clock, clear, and preset control signals on the flipflop can be driven by global signals, general-purpose I/O pins, or any internal logic. For combinational functions, the flipflop is bypassed and the LUT's output drives the LE's output.

The LE has two outputs that drive the interconnect: one drives the local interconnect, and the other drives either the row or column FastTrack Interconnect routing structure. The two outputs can be controlled independently. For example, the LUT can drive one output while the register drives the other output. This feature, called register packing, can improve LE utilization because the register and the LUT can be used for unrelated functions.

The ACEX 1K architecture provides two types of dedicated high-speed data paths that connect adjacent LEs without using local interconnect paths: carry chains and cascade chains. The carry chain supports high-speed counters and adders, and the cascade chain implements wide-input functions with minimum delay. Carry and cascade chains connect all LEs in a LAB and all LABs in the same row. Intensive use of carry and cascade chains can reduce routing flexibility. Therefore, the use of these chains should be limited to speed-critical portions of a design.

Figure 9. ACEX 1K Carry Chain Operation (n-Bit Full Adder)



### Normal Mode

The normal mode is suitable for general logic applications and wide decoding functions that can take advantage of a cascade chain. In normal mode, four data inputs from the LAB local interconnect and the carry-in are inputs to a 4-input LUT. The compiler automatically selects the carry-in or the DATA3 signal as one of the inputs to the LUT. The LUT output can be combined with the cascade-in signal to form a cascade chain through the cascade-out signal. Either the register or the LUT can be used to drive both the local interconnect and the FastTrack Interconnect routing structure at the same time.

The LUT and the register in the LE can be used independently (register packing). To support register packing, the LE has two outputs; one drives the local interconnect, and the other drives the FastTrack Interconnect routing structure. The DATA4 signal can drive the register directly, allowing the LUT to compute a function that is independent of the registered signal; a 3-input function can be computed in the LUT, and a fourth independent signal can be registered. Alternatively, a 4-input function can be generated, and one of the inputs to this function can be used to drive the register. The register in a packed LE can still use the clock enable, clear, and preset signals in the LE. In a packed LE, the register can drive the FastTrack Interconnect routing structure while the LUT drives the local interconnect, or vice versa.

### Arithmetic Mode

The arithmetic mode offers two 3-input LUTs that are ideal for implementing adders, accumulators, and comparators. One LUT computes a 3-input function; the other generates a carry output. As shown in [Figure 11](#), the first LUT uses the carry-in signal and two data inputs from the LAB local interconnect to generate a combinatorial or registered output. For example, in an adder, this output is the sum of three signals: a, b, and carry-in. The second LUT uses the same three signals to generate a carry-out signal, thereby creating a carry chain. The arithmetic mode also supports simultaneous use of the cascade chain.

### Up/Down Counter Mode

The up/down counter mode offers counter enable, clock enable, synchronous up/down control, and data loading options. These control signals are generated by the data inputs from the LAB local interconnect, the carry-in signal, and output feedback from the programmable register. Two 3-input LUTs are used; one generates the counter data, and the other generates the fast carry bit. A 2-to-1 multiplexer provides synchronous loading. Data can also be loaded asynchronously with the clear and preset register control signals without using the LUT resources.

### Clearable Counter Mode

The clearable counter mode is similar to the up/down counter mode, but it supports a synchronous clear instead of the up/down control. The clear function is substituted for the cascade-in signal in the up/down counter mode. Two 3-input LUTs are used; one generates the counter data, and the other generates the fast carry bit. Synchronous loading is provided by a 2-to-1 multiplexer. The output of this multiplexer is ANDed with a synchronous clear signal.

### *Internal Tri-State Emulation*

Internal tri-state emulation provides internal tri-states without the limitations of a physical tri-state bus. In a physical tri-state bus, the tri-state buffers' output enable (OE) signals select which signal drives the bus. However, if multiple OE signals are active, contending signals can be driven onto the bus. Conversely, if no OE signals are active, the bus will float. Internal tri-state emulation resolves contending tri-state buffers to a low value and floating buses to a high value, thereby eliminating these problems. The Altera software automatically implements tri-state bus functionality with a multiplexer.

### *Clear & Preset Logic Control*

Logic for the programmable register's clear and preset functions is controlled by the DATA3, LABCTRL1, and LABCTRL2 inputs to the LE. The clear and preset control structure of the LE asynchronously loads signals into a register. Either LABCTRL1 or LABCTRL2 can control the asynchronous clear. Alternatively, the register can be set up so that LABCTRL1 implements an asynchronous load. The data to be loaded is driven to DATA3; when LABCTRL1 is asserted, DATA3 is loaded into the register.

During compilation, the compiler automatically selects the best control signal implementation. Because the clear and preset functions are active-low, the Compiler automatically assigns a logic high to an unused clear or preset.

The clear and preset logic is implemented in one of the following six modes chosen during design entry:

- Asynchronous clear
- Asynchronous preset
- Asynchronous clear and preset
- Asynchronous load with clear
- Asynchronous load with preset
- Asynchronous load without clear or preset

When dedicated inputs drive non-inverted and inverted peripheral clears, clock enables, and output enables, two signals on the peripheral control bus will be used.

**Table 7** lists the sources for each peripheral control signal and shows how the output enable, clock enable, clock, and clear signals share 12 peripheral control signals. **Table 7** also shows the rows that can drive global signals.

*Table 7. Peripheral Bus Sources for ACEX Devices*

Peripheral Control Signal	EP1K10	EP1K30	EP1K50	EP1K100
OE0	Row A	Row A	Row A	Row A
OE1	Row A	Row B	Row B	Row C
OE2	Row B	Row C	Row D	Row E
OE3	Row B	Row D	Row F	Row L
OE4	Row C	Row E	Row H	Row I
OE5	Row C	Row F	Row J	Row K
CLKENA0/CLK0/GLOBAL0	Row A	Row A	Row A	Row F
CLKENA1/OE6/GLOBAL1	Row A	Row B	Row C	Row D
CLKENA2/CLR0	Row B	Row C	Row E	Row B
CLKENA3/OE7/GLOBAL2	Row B	Row D	Row G	Row H
CLKENA4/CLR1	Row C	Row E	Row I	Row J
CLKENA5/CLK1/GLOBAL3	Row C	Row F	Row J	Row G

Signals on the peripheral control bus can also drive the four global signals, referred to as GLOBAL0 through GLOBAL3. An internally generated signal can drive a global signal, providing the same low-skew, low-delay characteristics as a signal driven by an input pin. An LE drives the global signal by driving a row line that drives the peripheral bus which then drives the global signal. This feature is ideal for internally generated clear or clock signals with high fan-out. However, internally driven global signals offer no advantage over the general-purpose interconnect for routing data signals.

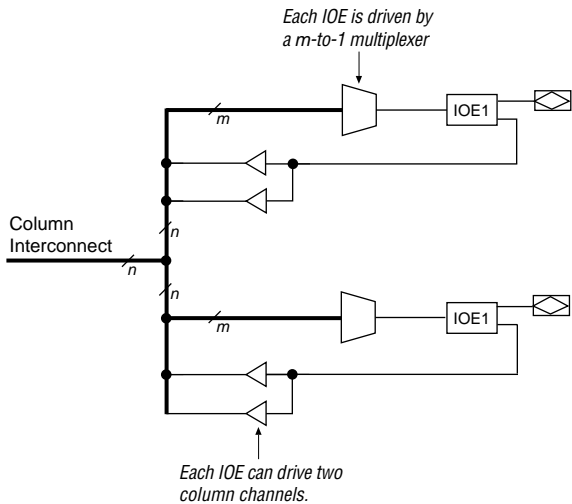
The chip-wide output enable pin is an active-high pin that can be used to tri-state all pins on the device. This option can be set in the Altera software. The built-in I/O pin pull-up resistors (which are active during configuration) are active when the chip-wide output enable pin is asserted. The registers in the IOE can also be reset by the chip-wide reset pin.



Column-to-IOE Connections

When an IOE is used as an input, it can drive up to two separate column channels. When an IOE is used as an output, the signal is driven by a multiplexer that selects a signal from the column channels. Two IOEs connect to each side of the column channels. Each IOE can be driven by column channels via a multiplexer. The set of column channels is different for each IOE (see Figure 17).

Figure 17. ACEX 1K Column-to-IOE Connections Note (1)



**Note:**

- (1) The values for  $m$  and  $n$  are shown in Table 9.

Table 9 lists the ACEX 1K column-to-IOE interconnect resources.

Table 9. ACEX 1K Column-to-IOE Interconnect Resources		
Device	Channels per Column ( $n$ )	Column Channels per Pin ( $m$ )
EP1K10	24	16
EP1K30	24	16
EP1K50	24	16
EP1K100	24	16



For more information, search for “SameFrame” in MAX+PLUS II Help.

*Table 10. ACEX 1K SameFrame Pin-Out Support*

Device	256-Pin FineLine BGA	484-Pin FineLine BGA
EP1K10	✓	(1)
EP1K30	✓	(1)
EP1K50	✓	✓
EP1K100	✓	✓

**Note:**

- (1) This option is supported with a 256-pin FineLine BGA package and SameFrame migration.

## ClockLock & ClockBoost Features

To support high-speed designs, -1 and -2 speed grade ACEX 1K devices offer ClockLock and ClockBoost circuitry containing a phase-locked loop (PLL) that is used to increase design speed and reduce resource usage. The ClockLock circuitry uses a synchronizing PLL that reduces the clock delay and skew within a device. This reduction minimizes clock-to-output and setup times while maintaining zero hold times. The ClockBoost circuitry, which provides a clock multiplier, allows the designer to enhance device area efficiency by sharing resources within the device. The ClockBoost feature allows the designer to distribute a low-speed clock and multiply that clock on-device. Combined, the ClockLock and ClockBoost features provide significant improvements in system performance and bandwidth.

The ClockLock and ClockBoost features in ACEX 1K devices are enabled through the Altera software. External devices are not required to use these features. The output of the ClockLock and ClockBoost circuits is not available at any of the device pins.

The ClockLock and ClockBoost circuitry lock onto the rising edge of the incoming clock. The circuit output can drive the clock inputs of registers only; the generated clock cannot be gated or inverted.

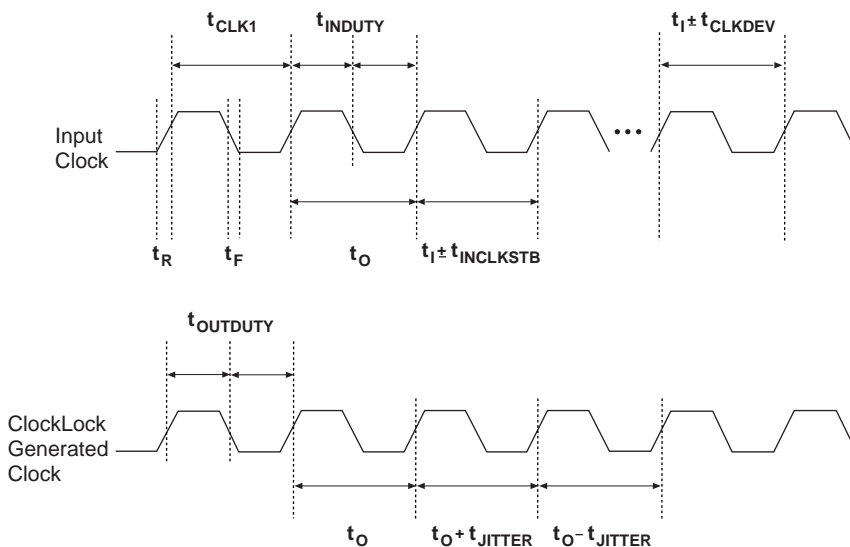
The dedicated clock pin (GCLK1) supplies the clock to the ClockLock and ClockBoost circuitry. When the dedicated clock pin is driving the ClockLock or ClockBoost circuitry, it cannot drive elsewhere in the device.

For designs that require both a multiplied and non-multiplied clock, the clock trace on the board can be connected to the GCLK1 pin. In the Altera software, the GCLK1 pin can feed both the ClockLock and ClockBoost circuitry in the ACEX 1K device. However, when both circuits are used, the other clock pin cannot be used.

### ClockLock & ClockBoost Timing Parameters

For the ClockLock and ClockBoost circuitry to function properly, the incoming clock must meet certain requirements. If these specifications are not met, the circuitry may not lock onto the incoming clock, which generates an erroneous clock within the device. The clock generated by the ClockLock and ClockBoost circuitry must also meet certain specifications. If the incoming clock meets these requirements during configuration, the ClockLock and ClockBoost circuitry will lock onto the clock during configuration. The circuit will be ready for use immediately after configuration. Figure 19 shows the incoming and generated clock specifications.

Figure 19. Specifications for the Incoming & Generated Clocks *Note (1)*



**Note:**

- (1) The  $t_I$  parameter refers to the nominal input clock period; the  $t_O$  parameter refers to the nominal output clock period.

## PCI Pull-Up Clamping Diode Option

ACEX 1K devices have a pull-up clamping diode on every I/O, dedicated input, and dedicated clock pin. PCI clamping diodes clamp the signal to the  $V_{CCIO}$  value and are required for 3.3-V PCI compliance. Clamping diodes can also be used to limit overshoot in other systems.

Clamping diodes are controlled on a pin-by-pin basis. When  $V_{CCIO}$  is 3.3 V, a pin that has the clamping diode option turned on can be driven by a 2.5-V or 3.3-V signal, but not a 5.0-V signal. When  $V_{CCIO}$  is 2.5 V, a pin that has the clamping diode option turned on can be driven by a 2.5-V signal, but not a 3.3-V or 5.0-V signal. Additionally, a clamping diode can be activated for a subset of pins, which allows a device to bridge between a 3.3-V PCI bus and a 5.0-V device.

## Slew-Rate Control

The output buffer in each IOE has an adjustable output slew rate that can be configured for low-noise or high-speed performance. A slower slew rate reduces system noise and adds a maximum delay of 4.3 ns. The fast slew rate should be used for speed-critical outputs in systems that are adequately protected against noise. Designers can specify the slew rate pin-by-pin or assign a default slew rate to all pins on a device-wide basis. The slow slew rate setting affects only the falling edge of the output.

## Open-Drain Output Option

ACEX 1K devices provide an optional open-drain output (electrically equivalent to open-collector output) for each I/O pin. This open-drain output enables the device to provide system-level control signals (e.g., interrupt and write enable signals) that can be asserted by any of several devices. It can also provide an additional wired-OR plane.

## MultiVolt I/O Interface

The ACEX 1K device architecture supports the MultiVolt I/O interface feature, which allows ACEX 1K devices in all packages to interface with systems of differing supply voltages. These devices have one set of  $V_{CC}$  pins for internal operation and input buffers ( $V_{CCINT}$ ), and another set for I/O output drivers ( $V_{CCIO}$ ).

**Table 16. 32-Bit IDCODE for ACEX 1K Devices** *Note (1)*

Device	IDCODE (32 Bits)			
	Version (4 Bits)	Part Number (16 Bits)	Manufacturer's Identity (11 Bits)	1 (1 Bit) <i>(2)</i>
EP1K10	0001	0001 0000 0001 0000	000011011110	1
EP1K30	0001	0001 0000 0011 0000	000011011110	1
EP1K50	0001	0001 0000 0101 0000	000011011110	1
EP1K100	0010	0000 0001 0000 0000	000011011110	1

**Notes to tables:**

- (1) The most significant bit (MSB) is on the left.  
 (2) The least significant bit (LSB) for all JTAG IDCODEs is 1.

ACEX 1K devices include weak pull-up resistors on the JTAG pins.



For more information, see the following documents:

- *Application Note 39 (IEEE Std. 1149.1 (JTAG) Boundary-Scan Testing in Altera Devices)*
- *ByteBlasterMV Parallel Port Download Cable Data Sheet*
- *BitBlaster Serial Download Cable Data Sheet*
- *Jam Programming & Test Language Specification*

Figure 20 shows the timing requirements for the JTAG signals.

Figure 22 shows the required relationship between  $V_{CCIO}$  and  $V_{CCINT}$  to satisfy 3.3-V PCI compliance.

Figure 22. Relationship between  $V_{CCIO}$  &  $V_{CCINT}$  for 3.3-V PCI Compliance

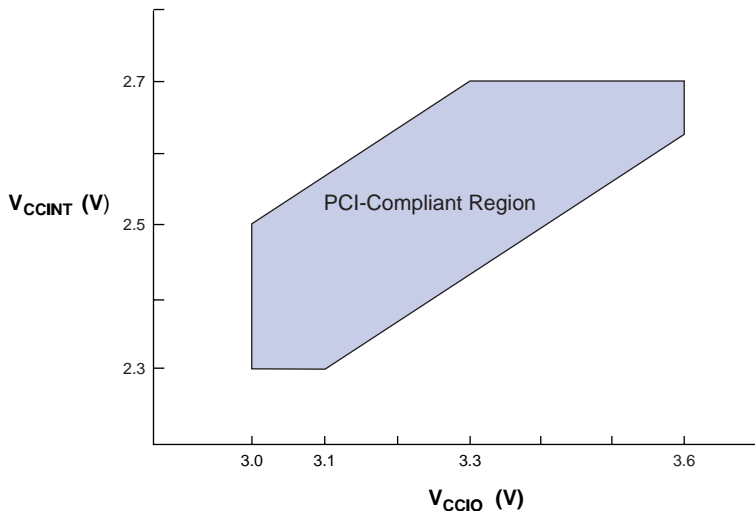


Figure 23 shows the typical output drive characteristics of ACEX 1K devices with 3.3-V and 2.5-V  $V_{CCIO}$ . The output driver is compliant to the **3.3-V PCI Local Bus Specification, Revision 2.2** (when  $V_{CCIO}$  pins are connected to 3.3 V). ACEX 1K devices with a -1 speed grade also comply with the drive strength requirements of the **PCI Local Bus Specification, Revision 2.2** (when  $V_{CCINT}$  pins are powered with a minimum supply of 2.375 V, and  $V_{CCIO}$  pins are connected to 3.3 V). Therefore, these devices can be used in open 5.0-V PCI systems.

Table 25. EAB Timing Macroparameters *Notes (1), (6)*

Symbol	Parameter	Conditions
$t_{EABAA}$	EAB address access delay	
$t_{EABRCCOMB}$	EAB asynchronous read cycle time	
$t_{EABRCREG}$	EAB synchronous read cycle time	
$t_{EABWP}$	EAB write pulse width	
$t_{EABWCCOMB}$	EAB asynchronous write cycle time	
$t_{EABWCREG}$	EAB synchronous write cycle time	
$t_{EABDD}$	EAB data-in to data-out valid delay	
$t_{EABDATACO}$	EAB clock-to-output delay when using output registers	
$t_{EABDATASU}$	EAB data/address setup time before clock when using input register	
$t_{EABDATAH}$	EAB data/address hold time after clock when using input register	
$t_{EABWESU}$	EAB $\overline{WE}$ setup time before clock when using input register	
$t_{EABWEH}$	EAB $\overline{WE}$ hold time after clock when using input register	
$t_{EABWDSU}$	EAB data setup time before falling edge of write pulse when not using input registers	
$t_{EABWDH}$	EAB data hold time after falling edge of write pulse when not using input registers	
$t_{EABWASU}$	EAB address setup time before rising edge of write pulse when not using input registers	
$t_{EABWAH}$	EAB address hold time after falling edge of write pulse when not using input registers	
$t_{EABWO}$	EAB write enable to data output valid delay	

Tables 27 through 29 describe the ACEX 1K external timing parameters and their symbols.

Table 27. External Reference Timing Parameters *Note (1)*

Symbol	Parameter	Conditions
$t_{\text{DRR}}$	Register-to-register delay via four LEs, three row interconnects, and four local interconnects	(2)

Table 28. External Timing Parameters

Symbol	Parameter	Conditions
$t_{\text{INSU}}$	Setup time with global clock at IOE register	(3)
$t_{\text{INH}}$	Hold time with global clock at IOE register	(3)
$t_{\text{OUTCO}}$	Clock-to-output delay with global clock at IOE register	(3)
$t_{\text{PCISU}}$	Setup time with global clock for registers used in PCI designs	(3), (4)
$t_{\text{PCIH}}$	Hold time with global clock for registers used in PCI designs	(3), (4)
$t_{\text{PCICO}}$	Clock-to-output delay with global clock for registers used in PCI designs	(3), (4)

Table 29. External Bidirectional Timing Parameters *Note (3)*

Symbol	Parameter	Conditions
$t_{\text{INSUBIDIR}}$	Setup time for bidirectional pins with global clock at same-row or same-column LE register	
$t_{\text{INHBIDIR}}$	Hold time for bidirectional pins with global clock at same-row or same-column LE register	
$t_{\text{OUTCOBIDIR}}$	Clock-to-output delay for bidirectional pins with global clock at IOE register	CI = 35 pF
$t_{\text{XZBIDIR}}$	Synchronous IOE output buffer disable delay	CI = 35 pF
$t_{\text{ZXBIDIR}}$	Synchronous IOE output buffer enable delay, slow slew rate = off	CI = 35 pF

**Notes to tables:**

- (1) External reference timing parameters are factory-tested, worst-case values specified by Altera. A representative subset of signal paths is tested to approximate typical device applications.
- (2) Contact Altera Applications for test circuit specifications and test conditions.
- (3) These timing parameters are sample-tested only.
- (4) This parameter is measured with the measurement and test conditions, including load, specified in the *PCI Local Bus Specification, Revision 2.2*.



Table 47. EP1K50 Device EAB Internal Timing Macroparameters *Note (1)*

Symbol	Speed Grade						Unit
	-1		-2		-3		
	Min	Max	Min	Max	Min	Max	
$t_{EABAA}$		3.7		5.2		7.0	ns
$t_{EABRCCOMB}$	3.7		5.2		7.0		ns
$t_{EABRCREG}$	3.5		4.9		6.6		ns
$t_{EABWP}$	2.0		2.8		3.8		ns
$t_{EABWCCOMB}$	4.5		6.3		8.6		ns
$t_{EABWCREG}$	5.6		7.8		10.6		ns
$t_{EABDD}$		3.8		5.3		7.2	ns
$t_{EABDATA CO}$		0.8		1.1		1.5	ns
$t_{EABDATASU}$	1.1		1.6		2.1		ns
$t_{EABDATAH}$	0.0		0.0		0.0		ns
$t_{EABWESU}$	0.7		1.0		1.3		ns
$t_{EABWEH}$	0.4		0.6		0.8		ns
$t_{EABWDSU}$	1.2		1.7		2.2		ns
$t_{EABWDH}$	0.0		0.0		0.0		ns
$t_{EABWASU}$	1.6		2.3		3.0		ns
$t_{EABWAH}$	0.9		1.2		1.8		ns
$t_{EABWO}$		3.1		4.3		5.9	ns

Tables 51 through 57 show EP1K100 device internal and external timing parameters.

Table 51. EP1K100 Device LE Timing Microparameters *Note (1)*

Symbol	Speed Grade						Unit
	-1		-2		-3		
	Min	Max	Min	Max	Min	Max	
$t_{LUT}$		0.7		1.0		1.5	ns
$t_{CLUT}$		0.5		0.7		0.9	ns
$t_{RLUT}$		0.6		0.8		1.1	ns
$t_{PACKED}$		0.3		0.4		0.5	ns
$t_{EN}$		0.2		0.3		0.3	ns
$t_{CICO}$		0.1		0.1		0.2	ns
$t_{CGEN}$		0.4		0.5		0.7	ns
$t_{CGENR}$		0.1		0.1		0.2	ns
$t_{CASC}$		0.6		0.9		1.2	ns
$t_C$		0.8		1.0		1.4	ns
$t_{CO}$		0.6		0.8		1.1	ns
$t_{COMB}$		0.4		0.5		0.7	ns
$t_{SU}$	0.4		0.6		0.7		ns
$t_H$	0.5		0.7		0.9		ns
$t_{PRE}$		0.8		1.0		1.4	ns
$t_{CLR}$		0.8		1.0		1.4	ns
$t_{CH}$	1.5		2.0		2.5		ns
$t_{CL}$	1.5		2.0		2.5		ns

Table 53. EP1K100 Device EAB Internal Microparameters *Note (1)*

Symbol	Speed Grade						Unit
	-1		-2		-3		
	Min	Max	Min	Max	Min	Max	
$t_{EABDATA1}$		1.5		2.0		2.6	ns
$t_{EABDATA1}$		0.0		0.0		0.0	ns
$t_{EABWE1}$		1.5		2.0		2.6	ns
$t_{EABWE2}$		0.3		0.4		0.5	ns
$t_{EABRE1}$		0.3		0.4		0.5	ns
$t_{EABRE2}$		0.0		0.0		0.0	ns
$t_{EABCLK}$		0.0		0.0		0.0	ns
$t_{EABCO}$		0.3		0.4		0.5	ns
$t_{EABYPASS}$		0.1		0.1		0.2	ns
$t_{EABSU}$	0.8		1.0		1.4		ns
$t_{EABH}$	0.1		0.1		0.2		ns
$t_{EABCLR}$	0.3		0.4		0.5		ns
$t_{AA}$		4.0		5.1		6.6	ns
$t_{WP}$	2.7		3.5		4.7		ns
$t_{RP}$	1.0		1.3		1.7		ns
$t_{WDSU}$	1.0		1.3		1.7		ns
$t_{WDH}$	0.2		0.2		0.3		ns
$t_{WASU}$	1.6		2.1		2.8		ns
$t_{WAH}$	1.6		2.1		2.8		ns
$t_{RASU}$	3.0		3.9		5.2		ns
$t_{RAH}$	0.1		0.1		0.2		ns
$t_{WO}$		1.5		2.0		2.6	ns
$t_{DD}$		1.5		2.0		2.6	ns
$t_{EABOUT}$		0.2		0.3		0.3	ns
$t_{EABCH}$	1.5		2.0		2.5		ns
$t_{EABCL}$	2.7		3.5		4.7		ns

The  $I_{CCACTIVE}$  value can be calculated with the following equation:

$$I_{CCACTIVE} = K \times f_{MAX} \times N \times \text{tog}_{LC} \text{ (}\mu\text{A)}$$

Where:

- $f_{MAX}$  = Maximum operating frequency in MHz
- $N$  = Total number of LEs used in the device
- $\text{tog}_{LC}$  = Average percent of LEs toggling at each clock (typically 12.5%)
- $K$  = Constant

Table 58 provides the constant (K) values for ACEX 1K devices.

Table 58. ACEX 1K Constant Values	
Device	K Value
EP1K10	4.5
EP1K30	4.5
EP1K50	4.5
EP1K100	4.5

This supply power calculation provides an  $I_{CC}$  estimate based on typical conditions with no output load. The actual  $I_{CC}$  should be verified during operation because this measurement is sensitive to the actual pattern in the device and the environmental operating conditions.

To better reflect actual designs, the power model (and the constant K in the power calculation equations) for continuous interconnect ACEX 1K devices assumes that LEs drive FastTrack Interconnect channels. In contrast, the power model of segmented FPGAs assumes that all LEs drive only one short interconnect segment. This assumption may lead to inaccurate results when compared to measured power consumption for actual designs in segmented FPGAs.

Figure 31 shows the relationship between the current and operating frequency of ACEX 1K devices. For information on other ACEX 1K devices, contact Altera Applications at (800) 800-EPLD.



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